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Delivery & Lifecycle Information ;

**503480-0600**

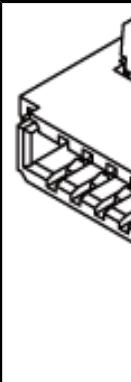
Molex

FFC & FPC Connectors .5mm FPC 6P CONN RA SMT B-FLIP DUAL

Any questions, please feel free to contact us.

[info@kaimte.com](mailto:info@kaimte.com)

**Part Number:** [5034800600](#)  
**Status:** **Active**  
**Description:** 0.50mm (.020") Pitch Easy-On™ BackFlip™ FPC Connector, 1.00mm (.039") Height, Right Angle, SMT, Dual Contact Style, 6 Circuits



**Documents:**

<a href="#">3D Model</a>	<a href="#">Product Specification PS-503480-001 (PDF)</a>
<a href="#">Drawing (PDF)</a>	<a href="#">RoHS Certificate of Compliance (PDF)</a>

**General**

Product Family	FFC/FPC Connectors
Series	503480
Product Name	BackFlip™, Easy-On™

**Physical**

Circuits (Loaded)	6
Color - Resin	Black, White
Contact Position	Dual
Durability (mating cycles max)	10
Entry Angle	90° Angle
Mated Height (in)	0.039 In
Mated Height (mm)	1.00 mm
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Gold, Tin
Number of Rows	1
Orientation	Right Angle
PCB Locator	No
PCB Retention	Yes
Packaging Type	Embossed Tape on Reel
Pitch - Mating Interface (in)	0.020 In
Pitch - Mating Interface (mm)	0.50 mm
Polarized to PCB	Yes
Stackable	No
Temperature Range - Operating	-40°C to +85°C
Termination Interface: Style	Surface Mount
Wire/Cable Type	FFC/FPC

**Electrical**

Current - Maximum per Contact	0.5A
Voltage - Maximum	50V AC (RMS)/DC

**Material Info**

**Reference - Drawing Numbers**

Packaging Specification	SPK-503480-001
Product Specification	PS-503480-001, RPS-503480-001, RPS-503480-002, RPS-503480-003
Sales Drawing	SD-503480-001, SD-503480-002

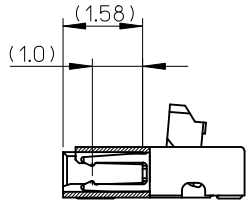
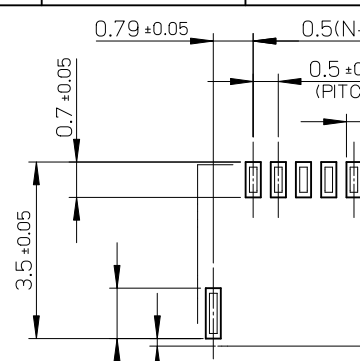
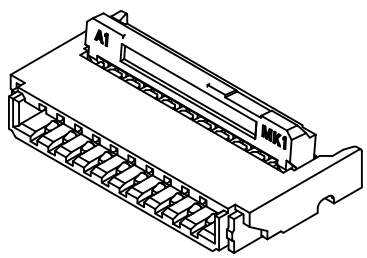
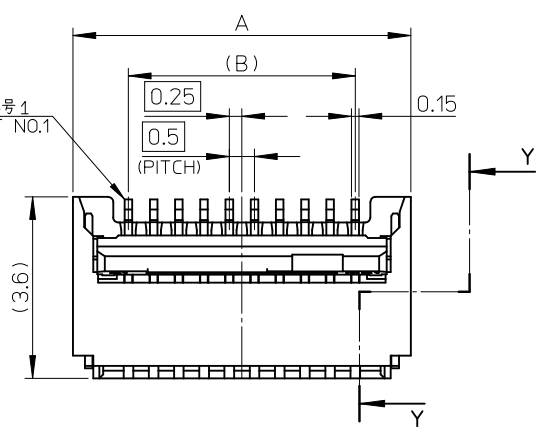
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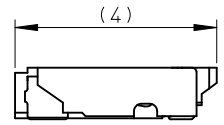
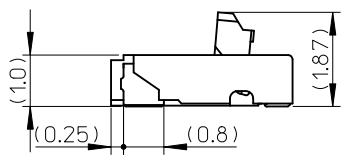
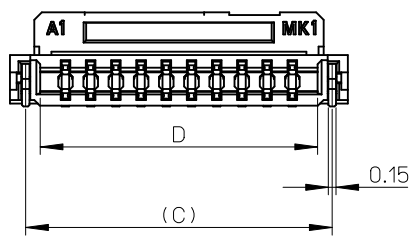
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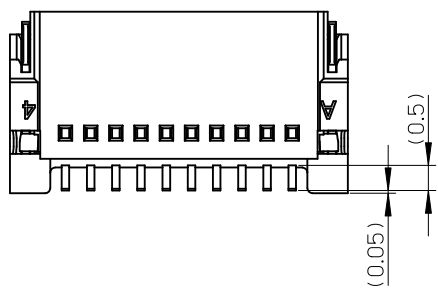
回路番号1  
CIRCUIT NO.1



SECTION Y-Y



アクチュエータが閉じた状態  
ACTUATOR CLOSED CONDITION



参考基板レイアウト  
P.W.BOARD PATTERN  
(MOUNT)

メタルマスク :  
開口部 : TER  
NAIL  
METAL MASK THICK  
OPENING AREA RATIO

16.5	17.
11.5	12.
10.5	11.
9.5	10.
9.0	9.
8.5	9.
7.5	8.
6.5	7.
5.5	6.
4.5	5.
3.5	4.
2.5	3.
D	C

REVISED	EC NO: J2010-2172	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	
	DRWN: THIRAYAMA 2010/04/29	10 UNDER	±0.2	DRAWN BY	DATE
	CHKD: NMATSUURA 2010/04/29	10 OVER 30 UNDER	±0.25	THIRAYAMA	2009/12/11
	APPR: KMORIKAWA 2010/05/12	30 OVER	±0.3	CHECKED BY	DATE
		ANGULAR	±1 °	NMATSUURA	2009/12/11
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE
				KMORIKAWA	2009/12/11
				MATERIAL NO.	
				SEE CHART	
				SIZE A3 THIS DRAWING CONTAINS INCORPORATED AND S	

NOTES

1. 部品構成

PART COMPOSITION

ハウジング・・・材質：液晶ポリマー（LCP）、ガラス充填、UL94V-0、ナチュラル（白）  
HOUSING MATERIAL: LIQUID CRYSTAL POLYMER(LCP), GLASS FILLED, UL94V-0, NATURAL(WHITE)

ターミナル・・・材質：燐青銅

TERMINAL MATERIAL: PHOSPHOR BRONZE

コンタクト部：部分金メッキ (0.1μm以上)

テール部：部分金メッキ

下地：ニッケルメッキ (1.0μm以上)

CONTACT AREA : SEPARATED GOLD PLATING

(0.1 MICROMETER MINIMUM)

SOLDER TAIL AREA : SEPARATED GOLD PLATING

UNDERPLATE : NICKEL OVERALL

(1.0 MICROMETER MINIMUM)

アクチュエータ・・・材質：ポリアミド（PA）、ガラス充填、UL94 HB、黒色  
ACTUATOR MATERIAL: POLYAMIDE(PA), GLASS FILLED, UL94 HB, BLACK

ネイル・・・材質：燐青銅

NAIL MATERIAL: PHOSPHOR BRONZE

テール部：錫メッキ (1.0μm以上)

下地：ニッケルメッキ (1.0μm以上)

SOLDER TAIL AREA : TIN OVERALL(1.0 MICROMETER MINIMUM)

UNDERPLATE : NICKEL OVERALL(1.0 MICROMETER MINIMUM)

2. 基板実装前にアクチュエータを操作しないで下さい。

PLEASE DO NOT OPERATE THE ACTUATOR BEFORE MOUNTING.

3. 必ずFPCを挿入してからアクチュエータを操作して下さい。

PLEASE OPERATE THE ACTUATOR AFTER INSERTING THE FPC INTO THE CONNECTOR.

4. FPCについて

ABOUT FPC

補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。

接着剤は熱硬化接着剤を推奨します。

尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

RECOMMENDED STIFFENER MATERIAL: POLYIMIDE

RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER

RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE

NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE

ON ADHEREND BECAUSE THERE IS A

POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES

THE DEFECT IN ELECTRICAL CONTINUITY.

打抜き方向は導体側から補強板側を推奨致します。

導体部については軟銅箔35μmを推奨致します。

RECOMMENDED PUNCHER DIRECTION:

FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.

RECOMMENDED CONDUCTOR SPECIFICATION:

THICKNESS OF SOFT COPPER FOIL: 35MICROMETER

△ R0.3は、FPC導体部にかからないこと。

R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

6. ELV及びRoHS適合品

ELV AND RoHS COMPLIANT

7. 平坦度：0.1以下

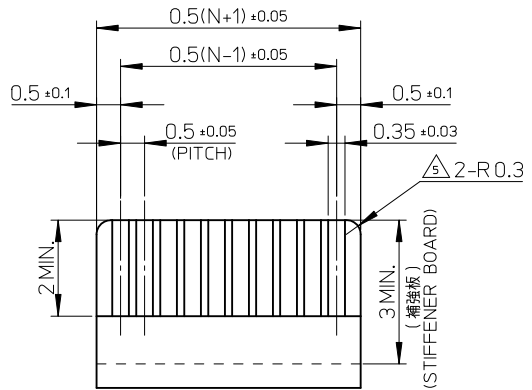
COPLANARITY : 0.1 MAXIMUM

8. 製造上の都合により機能を阻害しない部位の形状を変更する可能性があります。

PLEASE RECOGNIZE A POSSIBILITY TO CHANGE THE SHAPE

OF THE PART THAT DOES NOT OBSTRUCT A FUNCTION,

BY CIRCUMSTANCES IN OUR PRODUCTION.



適合FPC推奨寸法  
APPLICABLE FPC  
RECOMMENDED DIMENSION

N: 極数  
N: CIRCUITS

(仕上がり厚さ: 0.3±0.05) : 30極以下に適用  
(THICKNESS: 0.3±0.05) : 30 OR LESS CIRCUITS

(仕上がり厚さ: 0.3±0.03) : 31極以上に適用  
(THICKNESS: 0.3±0.03) : 31 OR OVER CIRCUITS

補強板: ポリイミド

REINFORCE BOARD: POLYIMIDE

熱硬化接着剤

THERMOSETTING ADHESIVE

ベースフィルム: ポリイミド (25μm)

BASE FILM: POLYIMIDE(25μm)

熱硬化接着剤

THERMOSETTING ADHESIVE

導体部: 銅箔 (35μm)

COPPER FOIL (35μm)

熱硬化接着剤

THERMOSETTING ADHESIVE

カバーレイ: ポリイミド (25μm)

COVER FILM: POLYIMIDE(25μm)

めっき: 金めっき (0.1μm)

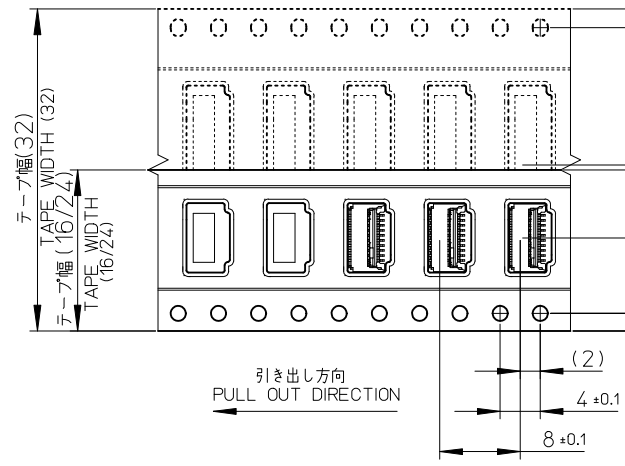
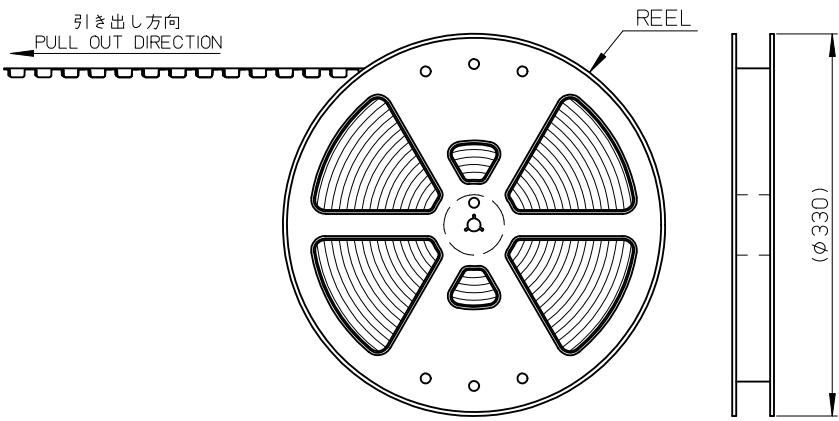
下地: ニッケル (1-5μm)

PLATING: GOLD(0.1μm)

NICKEL UN

FPC構成推奨仕様  
STRUCTURE OF FPC

SEE SHEET 1 EC NO.: J2010-2172 DRAWN: THIRAYAMA 2010/04/29 CHKD: MATSUURA 2010/04/29 APPR: KMORIKAWA 2010/05/12	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1
		10 UNDER	± 0.2	DRAWN BY THIRAYAMA	DATE 2009/12/11	TITLE
		10 OVER 30 UNDER	± 0.25	CHECKED BY NMATSUURA	DATE 2009/12/11	
		30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2009/12/11	
		ANGULAR	±1 °	MATERIAL NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		
REV		SIZE A3	THIS DRAWING CONTAINS INFO INCORPORATED AND SHOULD N			

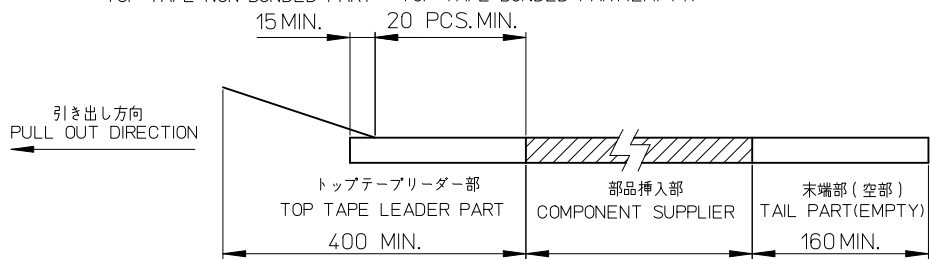


NOTES

1.製品(503480-\*\*09)の詳細寸法については、SD-503480-001をご参照下さい。  
IN THE PACKAGE, PART NO.503480-\*\*09 DETAILED DIMENSIONS.  
REFER TO SD-503480-001.

2.梱包数量 : 3000個/リール  
NUMBER OF CONNECTORS : 3000PCS/REEL

3.リードテープの長さ  
LEAD TAPE LENGTH  
トップテープ未接着部      トップテープ接着部(空エンボス)  
TOP TAPE NON-BONDED PART    TOP TAPE BONDED PART (EMPTY)



4.材料  
キャリアテープ : PET  
トップテープ : PET, OTHER  
リール : PS<リサイクル材を含む>

MATERIAL  
CARRIER TAPE : PET  
TOP TAPE : PET, OTHER  
REEL : PS <RECYCLE MATERIAL CONTAINED>

14.2	28.4	32
-	-	-
-	-	-
E	D	C

REVISED EC NO: J2010-2172 B DRWN: THIRAYAMA 2010/03/17 CHKD: NIMATSUURA 2010/04/29 APPR: KMORIKAWA 2010/05/12	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	
		10 UNDER	± 0.2	DRAWN BY	DATE
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				MATERIAL NO. SEE CHART	
				SIZE	THIS DRAWING CONTAINS INCORPORATED AND S
				A3	